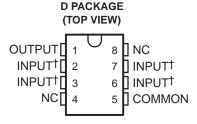
SLVS011D - OCTOBER 1982 - REVISED AUGUST 2003

- 3-Terminal Regulators
- Output Current Up To 100 mA
- No External Components Required
- Internal Thermal-Overload Protection
- Internal Short-Circuit Current Limiting
- Direct Replacement for Industry-Standard MC79L00 Series
- Available in 5% or 10% Selections

description/ordering information

This series of fixed negative-voltage integrated-circuit voltage regulators is designed for a wide range of applications. These include on-card regulation for elimination of noise and distribution problems associated with single-point



† Internally connected NC – No internal connection

LP PACKAGE (TOP VIEW)



regulation. In addition, they can be used to control series pass elements to make high-current voltage-regulator circuits. One of these regulators can deliver up to 100 mA of output current. The internal current-limiting and thermal-shutdown features essentially make the regulators immune to overload. When used as a replacement for a Zener-diode and resistor combination, these devices can provide an effective improvement in output impedance of two orders of magnitude, with lower bias current.

ORDERING INFORMATION

| TJ | OUTPUT VOLTAGE TOLERANCE | NOMINAL OUTPUT VOLTAGE (V) | PACKAG | Ε [†] | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|--------------|--------------------------------|-------------------------------------|----------------------|----------------|--------------------------|---------------------|
| | | | COIC (D) | Tube of 75 | MC79L05ACD | 701.054 |
| | 5% | _ | SOIC (D) | Reel of 2500 | MC79L05ACDR | 79L05A |
| | | -5 | TO 000 / TO 00 // D) | Bulk of 1000 | MC79L05ACLP | 701.0540 |
| | | | TO-226 / TO-92 (LP) | Reel of 2000 | MC79L05ACLPR | 79L05AC |
| | | -12 | 0010 (D) | Tube of 75 | MC79L12ACD | 701.404 |
| | | | SOIC (D) | Reel of 2500 | MC79L12ACDR | 79L12A |
| 0°C to 125°C | | | | Bulk of 1000 | MC79L12ACLP | 701.404.0 |
| | | | TO-226 / TO-92 (LP) | Reel of 2000 | MC79L12ACLPR | 79L12AC |
| | | | | Bulk of 1000 | MC79L15ACLP | |
| | | -15 | TO-226 / TO-92 (LP) | Ammo of 2000 | MC79L15ACLPM | 79L15AC |
| | | | | Reel of 2000 | MC79L15ACLPR | |
| | 400/ | -12 | TO-226 / TO-92 (LP) | Bulk of 1000 | MC79L12CLP | 79L12C |
| | 10% | -15 | SOIC (D) | Tube of 75 | MC79L15CD | 79L15C |

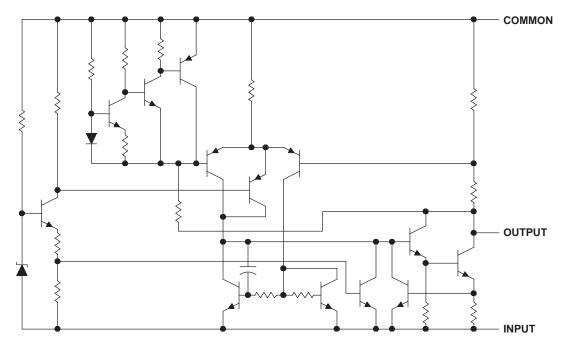
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



equivalent schematic



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Input voltage: MC79L05 | 30 V |
|---|--|
| MC79L12, MC79L15 | 35 V |
| Package thermal impedance, θ _{JA} (see Notes 1 and 2): D package | 97°C/W |
| LP package | 140°C/W |
| Operating free-air, case, or virtual junction temperature | 150°C |
| Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds | 260°C |
| Storage temperature range, T _{stg} | -65°C to 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

| | | | MIN | MAX | UNIT |
|----|--|---------|-------|-----|------|
| | | MC79L05 | -7 | -20 | |
| ٧į | Input voltage | MC79L12 | -14.5 | -27 | V |
| | | MC79L15 | -17.5 | -30 | |
| lo | Output current | | | 100 | mA |
| TJ | Operating virtual junction temperature | | 0 | 125 | °C |



NOTES: 1. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics at specified virtual junction temperature, $V_I = -10 \text{ V}$, $I_O = 40 \text{ mA}$ (unless otherwise noted)

| DADAMETED | TTOT COMPLETIONS! | - | M | C79L05 | С | МС | 79L05A | C | UNIT |
|----------------------|---|--------------|------|--------|------|-------|--------|-------|------|
| PARAMETER | TEST CONDITIONS† | TJ | MIN | TYP | MAX | MIN | TYP | MAX | UNII |
| | | 25°C | -4.6 | -5 | -5.4 | -4.8 | -5 | -5.2 | |
| Output voltage‡ | $V_I = -7 \text{ V to } -20 \text{ V},$ $I_O = 1 \text{ mA to } 40 \text{ mA}$ | 0°C to 125°C | -4.5 | | -5.5 | -4.75 | | -5.25 | V |
| | $V_I = -10 \text{ V}, I_O = 1 \text{ mA to } 70 \text{ mA}$ | 0°C to 125°C | -4.5 | | -5.5 | -4.75 | | -5.25 | |
| | V _I = -7 V to -20 V | 2500 | | | 200 | | | 150 | ., |
| Input regulation | $V_{I} = -8 \text{ V to } -20 \text{ V}$ | 25°C | | | 150 | | | 100 | mV |
| Ripple rejection | $V_I = -8 \text{ V to } -18 \text{ V, f} = 120 \text{ Hz}$ | 25°C | 40 | 49 | | 41 | 49 | | dB |
| Outrast as audation | I _O = 1 mA to 100 mA | 0500 | | | 60 | | | 60 | >/ |
| Output regulation | $I_O = 1 \text{ mA to } 40 \text{ mA}$ | 25°C | | | 30 | | | 30 | mV |
| Output noise voltage | f = 10 Hz to 100 kHz | 25°C | | 40 | | | 40 | | μV |
| Dropout voltage | I _O = 40 mA | 25°C | | 1.7 | | | 1.7 | | V |
| 5: | | 25°C | | | 6 | | | 6 | • |
| Bias current | | 125°C | | | 5.5 | | | 5.5 | mA |
| 5: | V _I = -8 V to -20 V | 202 / 4250 | | | 1.5 | | | 1.5 | |
| Bias current change | $I_O = 1 \text{ mA to } 40 \text{ mA}$ | 0°C to 125°C | | | 0.2 | | | 0.1 | mA |

[†] All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output. Pulse-testing techniques are used to maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. ‡ This specification applies only for dc power dissipation permitted by absolute maximum ratings.

electrical characteristics at specified virtual junction temperature, $V_I = -19 \text{ V}$, $I_O = 40 \text{ mA}$ (unless otherwise noted)

| 242445752 | | _ | M | C79L12 | С | МС | 79L12A | C | |
|----------------------|--|--------------|-------|--------|-------|-------|--------|-------|------|
| PARAMETER | TEST CONDITIONS† | TJ | MIN | TYP | MAX | MIN | TYP | MAX | UNIT |
| | | 25°C | -11.1 | -12 | -12.9 | -11.5 | -12 | -12.5 | |
| Output voltage‡ | $V_I = -14.5 \text{ V to } -27 \text{ V},$ $I_O = 1 \text{ mA to } 40 \text{ mA}$ | 0°C to 125°C | -10.8 | | -13.2 | -11.4 | | -12.6 | V |
| | $V_I = -19 \text{ V}, I_O = 1 \text{ mA to } 70 \text{ mA}$ | 0°C to 125°C | -10.8 | | -13.2 | -11.4 | | -12.6 | |
| | $V_{I} = -14.5 \text{ V to } -27 \text{ V}$ | 0500 | | | 250 | | | 250 | ., |
| Input regulation | V _I = -16 V to -27 V | 25°C | | | 200 | | 2 | | mV |
| Ripple rejection | $V_I = -15 \text{ V to } -25 \text{ V, f} = 120 \text{ Hz}$ | 25°C | 36 | 42 | | 37 | 42 | | dB |
| 0 | I _O = 1 mA to 100 mA | 0500 | | | 100 | | | 100 | ., |
| Output regulation | I _O = 1 mA to 40 mA | 25°C | 50 | | | 50 | | mV | |
| Output noise voltage | f = 10 Hz to 100 kHz | 25°C | | 80 | | | 80 | | μV |
| Dropout voltage | I _O = 40 mA | 25°C | | 1.7 | | | 1.7 | | V |
| 5. | | 25°C | | | 6.5 | | | 6.5 | • |
| Bias current | | 125°C | | | 6 | | | 6 | mA |
| D'an annual alcana | V _I = -16 V to -27 V | 000 1- 40500 | | | 1.5 | | | 1.5 | 4 |
| Bias current change | I _O = 1 mA to 40 mA | 0°C to 125°C | | | 0.2 | | | 0.1 | mA |

[†] All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output. Pulse-testing techniques are used to maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. ‡ This specification applies only for dc power dissipation permitted by absolute maximum ratings.



MC79L00 SERIES NEGATIVE-VOLTAGE REGULATORS

SLVS011D - OCTOBER 1982 - REVISED AUGUST 2003

electrical characteristics at specified virtual junction temperature, $V_I = -23~V,\,I_O = 40~mA$ (unless otherwise noted)

| DADAMETED | TTOT CONDITIONS! | _ | M | C79L15 | С | МС | 79L15 <i>A</i> | /C | UNIT |
|-----------------------|--|--------------|-------|--------|-------|--------|----------------|--------|------|
| PARAMETER | TEST CONDITIONS† | TJ | MIN | TYP | MAX | MIN | TYP | MAX | UNII |
| | | 25°C | -13.8 | -15 | -16.2 | -14.4 | -15 | -15.6 | |
| Output voltage‡ | $V_I = -17.5 \text{ V to } -30 \text{ V},$ $I_O = 1 \text{ mA to } 40 \text{ mA}$ | 0°C to 125°C | -13.5 | | -16.5 | -14.25 | | -15.75 | V |
| | $V_1 = -23 \text{ V}, I_0 = 1 \text{ mA to } 70 \text{ mA}$ | 0°C to 125°C | -13.5 | | -16.5 | -14.25 | | -15.75 | |
| lament na medations | $V_I = -17.5 \text{ V to } -30 \text{ V}$ | 0500 | | | 300 | | | 300 | \/ |
| Input regulation | $V_{I} = -17.5 \text{ V to } -30 \text{ V}$ | 25°C | | | 250 | | | 250 | mV |
| Ripple rejection | V _I = -18.5 V to -28.5 V, f = 120 Hz | 25°C | 33 | 39 | | 34 | 39 | | dB |
| Outside as and office | I _O = 1 mA to 100 mA | 0500 | | | 150 | | | 150 | >/ |
| Output regulation | I _O = 1 mA to 40 mA | 25°C | | | 75 | | | 75 | mV |
| Output noise voltage | f = 10 Hz to 100 kHz | 25°C | | 90 | | | 90 | | μV |
| Dropout voltage | I _O = 40 mA | 25°C | | 1.7 | | | 1.7 | | V |
| | | 25°C | | | 6.5 | | | 6.5 | |
| Bias current | | 125°C | | | 6 | | | 6 | mA |
| D'an annual alam | V _I = -20 V to -30 V | 000 1- 40500 | | | 1.5 | | | 1.5 | 4 |
| Bias current change | $I_O = 1 \text{ mA to } 40 \text{ mA}$ | 0°C to 125°C | | | 0.2 | | | 0.1 | mA |

[†] All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output. Pulse-testing techniques are used to maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. ‡ This specification applies only for dc power dissipation permitted by absolute maximum ratings.







24-Aug-2018

PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|--------|--------------|--------------------|------|----------------|----------------------------|------------------|--------------------|--------------|----------------------|---------|
| MC79L05ACD | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 125 | 79L05A | Samples |
| MC79L05ACDE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 125 | 79L05A | Sample |
| MC79L05ACDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 125 | 79L05A | Sample |
| MC79L05ACDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 125 | 79L05A | Sample |
| MC79L05ACDRE4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 125 | 79L05A | Sample |
| MC79L05ACDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 125 | 79L05A | Samples |
| MC79L05ACLP | ACTIVE | TO-92 | LP | 3 | 1000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | 0 to 125 | 79L05AC | Sample |
| MC79L05ACLPE3 | ACTIVE | TO-92 | LP | 3 | 1000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | 0 to 125 | 79L05AC | Sample |
| MC79L05ACLPR | ACTIVE | TO-92 | LP | 3 | 2000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | 0 to 125 | 79L05AC | Samples |
| MC79L12ACD | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 125 | 79L12A | Samples |
| MC79L12ACDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 125 | 79L12A | Samples |
| MC79L12ACLP | ACTIVE | TO-92 | LP | 3 | 1000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | 0 to 125 | 79L12AC | Samples |
| MC79L12ACLPE3 | ACTIVE | TO-92 | LP | 3 | 1000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | 0 to 125 | 79L12AC | Samples |
| MC79L12ACLPR | ACTIVE | TO-92 | LP | 3 | 2000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | 0 to 125 | 79L12AC | Samples |
| MC79L12ACLPRE3 | ACTIVE | TO-92 | LP | 3 | 2000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | 0 to 125 | 79L12AC | Sample |
| MC79L12CLP | ACTIVE | TO-92 | LP | 3 | 1000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | 0 to 125 | 79L12C | Samples |
| MC79L15ACLP | ACTIVE | TO-92 | LP | 3 | 1000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | 0 to 125 | 79L15AC | Samples |



PACKAGE OPTION ADDENDUM

24-Aug-2018

| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|--------|--------------|--------------------|------|----------------|-------------------|------------------|--------------------|--------------|----------------------|---------|
| MC79L15ACLPE3 | ACTIVE | TO-92 | LP | 3 | 1000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | 0 to 125 | 79L15AC | Samples |
| MC79L15ACLPR | ACTIVE | TO-92 | LP | 3 | 2000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | 0 to 125 | 79L15AC | Samples |
| MC79L15ACLPRE3 | ACTIVE | TO-92 | LP | 3 | 2000 | Pb-Free (RoHS) | CU SN | N / A for Pkg Type | 0 to 125 | 79L15AC | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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24-Aug-2018



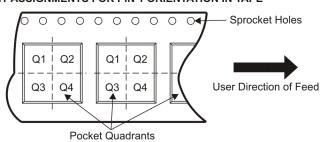
TAPE AND REEL INFORMATION



TAPE DIMENSIONS KO P1 BO W Cavity A0

| | Dimension designed to accommodate the component width |
|----|---|
| В0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

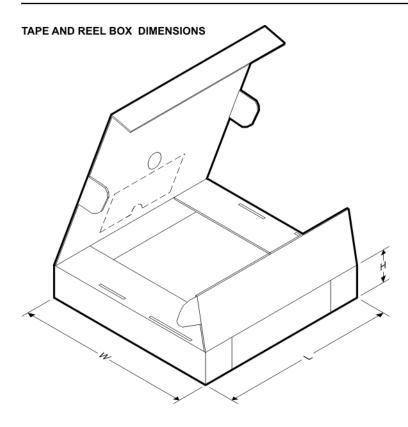
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|-----------------|--------------------|---|------|--------------------------|--------------------------|---------|---------|---------|------------|-----------|------------------|
| MC79L05ACDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| MC79L12ACDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |





*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|
| MC79L05ACDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| MC79L12ACDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040001-2/F



TO-92 - 5.34 mm max height

TO-92



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.
- 3. Lead dimensions are not controlled within this area.4. Reference JEDEC TO-226, variation AA.
- 5. Shipping method:

 - a. Straight lead option available in bulk pack only.
 b. Formed lead option available in tape and reel or ammo pack.
 - c. Specific products can be offered in limited combinations of shipping medium and lead options.
 - d. Consult product folder for more information on available options.



TO-92





TO-92





D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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